

REMARKS

Claims 1-26 are pending in this application. By this Amendment, claims 1, 5 and 11 are amended; and claims 17-26 are added.

I. The Claims Define Patentable Subject Matter

The Office Action rejects claims 1, 2, 5-7, 11, 14 and 15 under 35 U.S.C. §102(b) over U.S. Patent No. 5,514,613 to Santadrea et al.; and claims 3, 8, 9, 12 and 13 under 35 U.S.C. §103(a) over Santadrea et al. in view of U.S. Patent No. 5,530,262 to Cronin et al. These rejections are respectfully traversed.

Santadrea et al. does not teach, disclose or suggest "separating the metal wires and the insulating layer from the base upon irradiating through the base," as recited in claim 1, and as similarly recited in claims 5 and 11. The specification at paragraph [0047] discloses that at the time of separating the connection substrate from the first glass base, ultraviolet light or x-rays from the rear surface side of the first glass base is irradiated.

Instead, Santadrea et al. discloses that "the structure can be initially formed on an underlying carrier of selected material, even silicon, which later can be etched away or otherwise removed by any of several well-known processes, such as, for example, dry plasma etch or chemical-mechanical polish thereby to leave the interconnect structure 30 in a form as shown suitable" (Col. 4, lines 52-59). These methods of Santadrea et al. do not disclose or suggest irradiating through the base as claimed.

Cronin et al. does not make up for the deficiencies of Santadrea et al. Cronin et al. does not relate to any subject matter regarding separation of layers upon irradiating through a base.

Claims 17, 19 and 22 as added modify the features of claims 1, 5 and 11, respectively, to further recite that a base is a light transmissive base (like a glass); the surface on which a metal wire is formed is coated by a solvent having a separation reaction due to light; and

radiating light through the base. Support for these features may be found in the specification at paragraph [0047] and the effect of these features is cited in the specification at paragraph [0016]. The applied references do not teach, disclose or suggest at least these newly recited features of claims 17, 19 and 22.

For at least these reasons, it is respectfully submitted that claims 1, 5, 11, 17, 19 and 22 are patentable over the applied references. The dependent claims are likewise patentable over the applied references for at least the reasons discussed, as well as for the additional features they recite. Applicant respectfully requests that the rejections under 35 U.S.C. §§102(b) and 103(a) be withdrawn.

II. Conclusion

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1-16 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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Attachment:
Amendment Transmittal

JAO:RJK/sqb

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